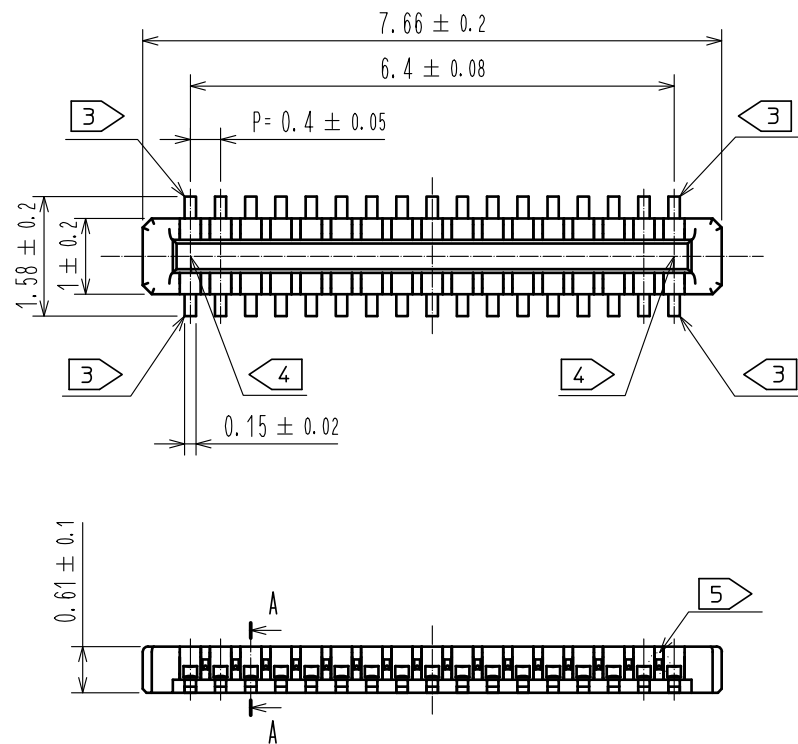
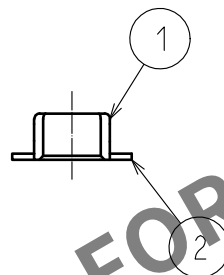
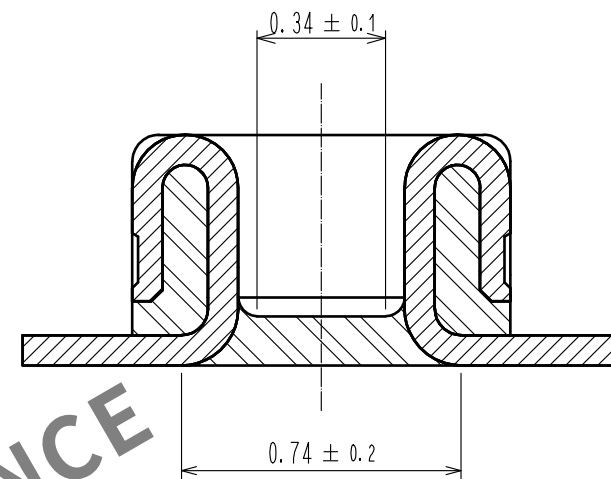




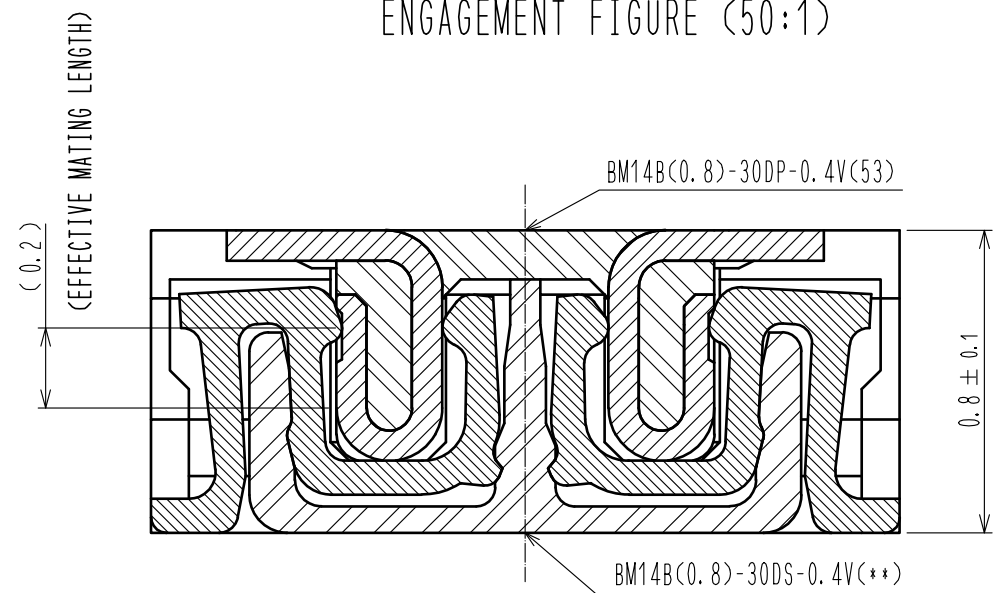
- NOTE) 1 . ALL LEAD CO-PLANARITY SHALL BE 0.08mm MAX
2 . CONTACT PLATING SPECIFICATIONS
CONTACT AREA : GOLD 0.05 μ m MIN
SMT LEAD : GOLD 0.05 μ m MIN
UNDERPLATING : NICKEL 1 μ m MIN
(SURFACE : SEALING)
3 . EACH CONTACTS AT 4 CORNERS ARE PROVIDED FOR METAL FITTINGS AND GROUNDING PURPOSE.
4 . HRS MARK AND CAV No. ARE INDICATED IN APPROX POSITION SHOWN.
5 . A PART OF THE WALL COULD BE NOTCHED.



A-A (50:1)

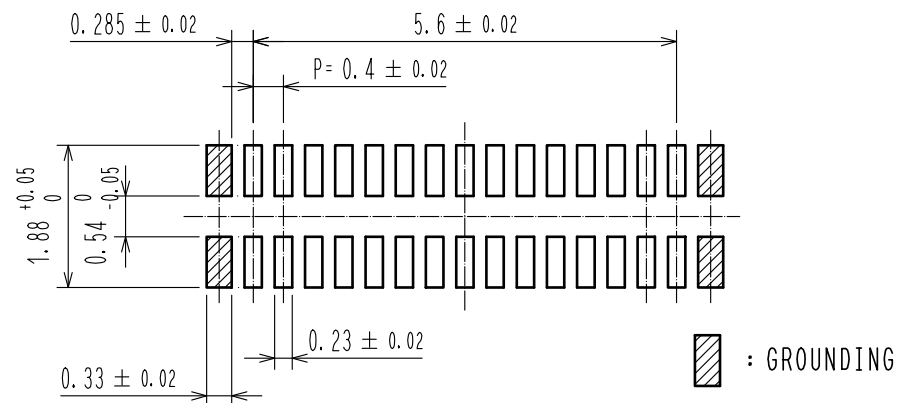


ENGAGEMENT FIGURE (50:1)



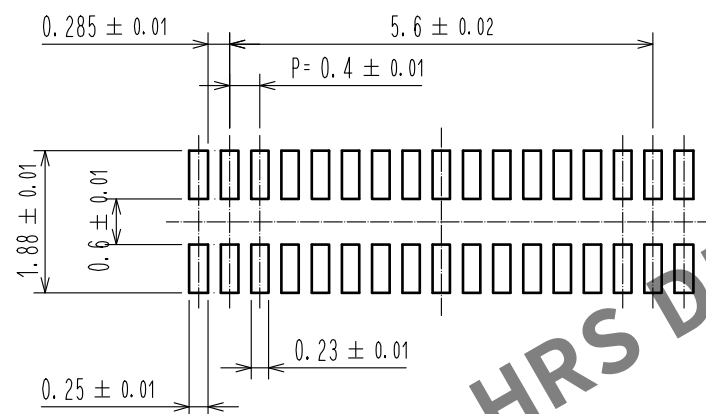
3	PS	CLEAR (ENBOSSED CARRIER TAPE)	6	PS	CLEAR (REINFORCEMENT COLLAR)
2	PHOSPHOR BRONZE	2	5	PS	BLACK (PLASTIC REEL)
1	LCP	UL94 V-0, BLACK	4	POLYESTER	CLEAR (COVER TAPE)
NO.	MATERIAL	FINISH , REMARKS	NO.	MATERIAL	FINISH , REMARKS
UNITS mm		SCALE 10 : 1	COUNT 1	DESCRIPTION OF REVISIONS	DESIGNED
HIROSE ELECTRIC CO., LTD.		APPROVED : MO. ISHIDA	17. 01. 19	DRAWING NO.	EDC-319848-53-00
		CHECKED : TS. MIYAZAKI	17. 01. 19	PART NO.	BM14B(0.8)-30DP-0.4V(53)
		DESIGNED : NY. YAMASHIRO	17. 01. 19	CODE NO.	CL684-8013-9-53
		DRAWN : SN. NUMAZAKI	17. 01. 18		

◆ RECOMMENDED PCB LAYOUT

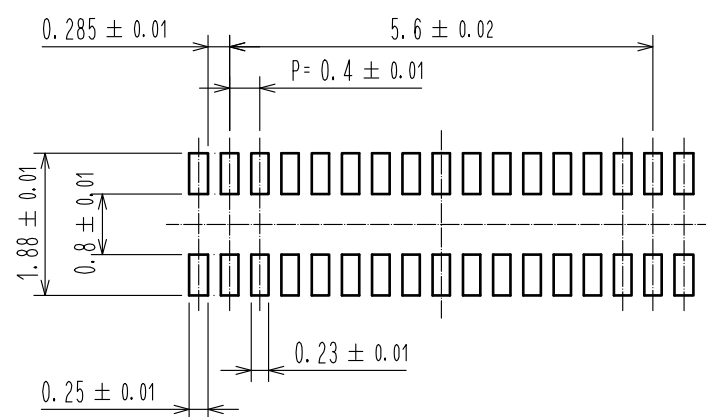


◆ RECOMMENDED METAL MASK DIMENSIONS

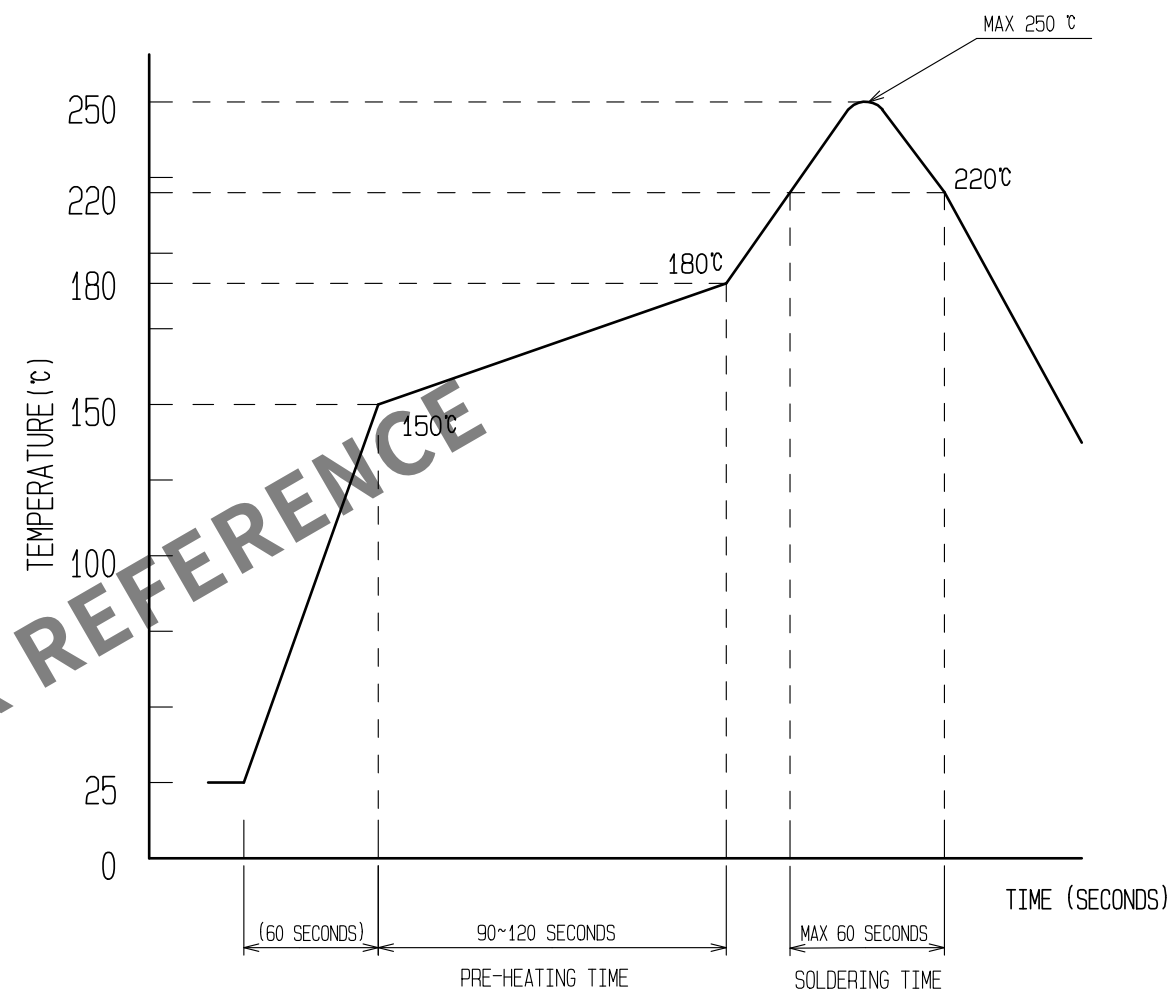
METAL MASK THICKNESS : $100 \mu\text{m}$



METAL MASK THICKNESS : $120 \mu\text{m}$



6 RECOMMENDED REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE.



REFLOW METHOD: IR REFLOW
NUMBER OF REFLOW CYCLES: 2 CYCLES MAX.

- 1) REFLOW TIME
DURATION ABOVE 220°C , 60 SEC. MAX.
(PEAK TEMPERATURE: 250°C MAX)
- 2) PRE-HEAT TIME
PRE-HEAT TEMPERATURE(MIN): 150°C
PRE-HEAT TEMPERATURE(MAX): 180°C
PRE-HEAT TIME: $90 \sim 120$ sec.

6 THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE. ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE, THEREFORE, A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.

HRS

DRAWING NO.	EDC-319848-53-00
PART NO.	BM14B<0.8>-30DP-0.4V<53>
CODE NO.	CL684-8013-9-53

2/3

